

WHAT IS CLAIMED IS:

1. A package structure to be mounted on an external printed circuit board, said package structure comprising:
- 5 a package board that is mounted with an exoergic circuit element; and
- a heat sink that radiates heat from the exoergic circuit element, wherein first pressure for connecting the heat sink to the package board is separated from second pressure for compressing the package board against the printed circuit
- 10 board.
2. A package structure according to claim 1, wherein the first pressure is less than the second pressure.
- 15 3. A package structure according to claim 1, wherein the first pressure is set to be about one tenth to about one fifth as large as the second pressure.
4. A package structure according to claim 1, further comprising a socket, provided on said package board, which electrically connects said package structure to
- 20 the printed circuit board.
5. The package structure according to claim 1, wherein said package board is made of resin.
- 25 6. A package structure according to claim 1, further comprising a heat spreader that thermally connects the heat sink to the exoergic circuit element, and has

a convex section.

7. A package structure according to claim 1, further comprising a heat spreader that thermally connects the heat sink to the exoergic circuit element, and is
5 not connected with the package board.

8. A package structure according to claim 1, wherein said heat sink is connected to the exoergic circuit element.

10 9. A package structure to be mounted onto an external printed circuit board, said package structure comprising:

a package board that is mounted with an exoergic circuit element;

a heat sink that radiates heat from the exoergic circuit element;

a stiffener located between the heat sink and the package board
15 around the exoergic circuit element;

a first pressure mechanism that presses one of the heat sink and the stiffener against the other; and

a second pressure mechanism that compresses the stiffener against the printed circuit board.

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10. A package structure according to claim 9, further comprising a socket, provided on the package board, which connects the package structure with the printed circuit board electrically.

25 11. A package structure according to claim 9, wherein the package board is made of resin.

12. A package structure according to claim 9, wherein the stiffener is larger than an external form of the package board.

13. A package structure according to claim 9, wherein the first and
5 second pressure mechanisms include:

two kind of elastic elements; and

a coupling member that couples two kind of the elastic elements to each other.

14. A package structure according to claim 9, wherein pressure applied
10 by the first pressure mechanism is smaller than that of the second pressure mechanism.

15. A package structure according to claim 9, wherein the stiffener
15 covers a connection part between the package board and the printed circuit board.

16. A package structure according to claim 9, wherein the first pressure mechanism is fixed onto the stiffener.

17. A package structure according to claim 9, further comprising a heat
20 spreader that thermally connects the heat sink with the exoergic circuit element, and has a convex section.

18. A package structure according to claim 9, further comprising a heat
25 spreader that thermally connects the heat sink with the exoergic circuit element, and is not connected with the package board.

19. A package structure according to claim 9, wherein said heat sink is connected to the exoergic circuit element.

20. A package structure according to claim 9, wherein said stiffener is
5 adhered to the package board.

21. A package structure according to claim 9, wherein said stiffener is made of stainless.

10 22. A package structure to be mounted on an external printed circuit board, said package structure comprising:

a resin package board that is mounted with an exoergic circuit element; and

a socket, provided onto said package board, which electrically
15 connects said package board to the printed circuit board.

23. A package structure according to claim 22, further comprising a mechanism that applies pressure to connect said socket to the printed circuit board and prevents the pressure from being applied to the exoergic circuit element.

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24. A printed circuit board which is mounted with a package structure, wherein said package structure includes:

a package board that is mounted with an exoergic circuit element;
and

25 a heat sink that radiates heat from the exoergic circuit element, wherein first pressure for connecting the heat sink with the package board is separated

from second pressure for compressing the package board against the printed circuit board.

25. An electronic apparatus that includes a printed circuit board that is
5 mounted with a package structure,

wherein said package structure includes:

a package board that is mounted with an exoergic circuit element;
and

a heat sink that radiates heat from the exoergic circuit element,
10 wherein first pressure for connecting the heat sink with the package board is separated
from second pressure for compressing the package board against the printed circuit
board.

26. A fixture component for a package structure comprising:
15 a stiffener, arranged between a package board mounted with an
exoergic circuit element, and a heat sink that radiates heat from the exoergic circuit
element;

a first pressure mechanism that compresses one of the heat sink and
the stiffener against the other; and

20 a second pressure mechanism that compresses said stiffener against
the printed circuit board onto which the package board is mounted with different
pressure from that of the first pressure mechanism.

27. The fixture component according to claim 26, wherein the pressure
25 by the first pressure mechanism is smaller than the pressure of the second pressure.

28. The fixture component according to claim 26, wherein said stiffener has a perforation, while the heat sink has first and second perforations,

wherein said first pressure mechanism includes a first component fixed onto the stiffener through the first perforation in the heat sink; and

5 wherein said second pressure mechanism includes a second component fixed onto the printed circuit board through the perforation of the stiffener.

29. A fixture component according to claim 26, wherein said stiffener has a first perforation, while the heat sink has first and second perforations,

10 wherein said first pressure mechanism includes a first component fixed onto the stiffener through the first perforation in the stiffener; and

wherein said second pressure mechanism includes a second component fixed onto the printed circuit board through the perforation of the heat sink.

15 30. The fixture component according to claim 26, wherein said first and second pressure mechanisms include:

two types of elastic members; and

20 a coupling member that couples the two types of elastic members to each other.